



DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

IN REPLY
REFER TO

DSCC-VQH-07-012347 (Miss Schneider/614-692-0585/js)

SUBJECT: Incoming Inspection Test for Palladium/Silver Finish, MIL-PRF-38534, FSC 5962

INDUSTRY DISTRIBUTION

Dear Sir or Madame:

We have been evaluating the methods used by our QML-38534 companies to prevent the use of pure-tin terminated components. Methods we have approved are listed below.

Finish	Acceptable Method of Finish Verification
Tin/lead	Specify termination material and % lead in drawing and/or purchase order. + Certificate of Compliance + Vendor materials analysis from every lot or sample X-Ray florescence on every lot.
Gold	Specify termination material in the drawing. + Certificate of Compliance + Visual inspection at incoming inspection.
Palladium/Silver	Specify termination material in the drawing. + Certificate of Compliance. + Subjecting a sample from each lot of components to one of the following. <u>Magnet Test</u> : This test is performed by putting the magnet near the termination. In the case of Palladium/Silver the part should not be attracted to the magnet. In the case of tin the magnet will be attracted by the Nickel under-plate. <u>Soldering Iron Test</u> : Apply a soldering iron hot enough to reflow the tin or tin/lead termination. Palladium/Silver has a much higher melting point. <u>X-Ray florescence</u>



When we began this process we thought that we could accept Palladium/Silver without the magnet or solder test, employing just a visual verification because of the visual difference between bright tin and Palladium/Silver. It has since then come to our attention that there is no distinct difference between matte tin and Palladium/Silver. Consequently we are asking all QML-38534 manufacturers to perform either the magnet or soldering iron test, X-Ray fluorescence, or another test to method to verify the Palladium/Silver.

Your company is not identified on our web site as using one of the approved methods to verify Palladium/Silver end termination finish. Please send your revised receiving inspection procedure to Binh Tonnu at this office within 14 days of the date of this letter.

Binh Tonnu
DSCC-VQH
PO Box 3990
Columbus, OH 43218-3990
Binh.tonnu@dla.mil

If you have any questions, please contact Miss Schneider at (614) 692-0585.

Sincerely,

JOSEPH GEMPERLINE
Chief
Hybrid Devices Team

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